

10-28-2002



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10/21/02

To the Honorable Commissioner of Patents and Trademarks, U.S. Patent and Trademark Office, Washington, D.C. 20231. Enclosed original documents or copy thereof.

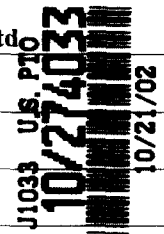
1. Name of conveying party(ies):

Hisahiro TANAKA
Matsuo MASUDA

2. Name and address of receiving party(ies):

Name: Matsushita Electric Industrial Co., Ltd

Internal Address:



Additional names(s) of conveying party(ies) Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Street Address: 1006, Oaza Kadoma, Kadoma-shi,
Osaka, JAPAN

City: _____ State: _____ ZIP: _____

Execution Date: October 9, 2002

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: October 9, 2002

A. Patent Application No.(s)

10/23/2002 WAFAM1 00000005 10274033

02 FC:8021

40.00 DP

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: James E. Ledbetter, Esq.

Internal Address: Registration No. 28,732

STEVENS, DAVIS, MILLER & MOSHER, LLP

L7016.02120

Street Address: 1615 L Street, N.W., Suite 850

City: Washington State: DC ZIP: 20036

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

Enclosed - Any excess or insufficiency should be credited or debited to deposit account

Authorized to be charged to deposit account

8. Deposit account number:

19-4375

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

James E. Ledbetter

October 21, 2002

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and document:

2

ASSIGNMENT

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar(\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., a corporation organized under the laws of Japan, located at 1006, Oaza Kadoma, Kadoma-shi, Osaka, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to "METHOD FOR PRODUCING TIN-SILVER ALLOY PLATING FILM, THE TIN-SILVER ALLOY PLATING FILM AND LEAD FRAME FOR ELECTRONIC PARTS HAVING THE PLATING FILM" invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith,

and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)	WITNESSES (立会人サイン)
1) <u>Hisahiro Tanaka</u> Hisahiro TANAKA	<u>October 9, 2002</u>	<u>Kazuhiko Sugimoto</u>
2) <u>Matsuo Masuda</u> Matsuo MASUDA	<u>October 9, 2002</u>	<u>Kazuhiko Sugimoto</u>
3) _____	_____	_____
4) _____	_____	_____
5) _____	_____	_____
6) _____	_____	_____
7) _____	_____	_____
8) _____	_____	_____
9) _____	_____	_____